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(12) **United States Design Patent**
Xiong

(10) **Patent No.:** **US D984,419 S**

(45) **Date of Patent:** **** Apr. 25, 2023**

(54) **WIRELESS EARBUD SET**

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EM 008449664-0001 * 3/2021

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(Continued)

(73) Assignee: **Shenzhen Shanzhong Technology Co., Ltd**, Shenzhen (CN)

Primary Examiner — Paula Allen Greene

(**) Term: **15 Years**

(57) **CLAIM**

(21) Appl. No.: **29/784,977**

The ornamental design for a wireless earbud set, as shown and described.

(22) Filed: **May 22, 2021**

DESCRIPTION

(30) **Foreign Application Priority Data**

Nov. 24, 2020 (CN) 202030712822.9

(51) **LOC (14) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/223**

(58) **Field of Classification Search**

USPC D14/223, 224; D24/174; 128/864-866;
D13/108; D3/201, 294, 274; D9/420,
D9/424, 529, 423; D28/76, 82;
220/4.22, 4.23; 381/322, 328

CPC H04R 1/10; H04R 25/00; H04R 25/02;
H04R 1/1066; H04R 1/1016; H04R
5/033; H04R 5/0335; H04R 1/1025;
B65D 5/00; B65D 43/02; B65D 25/10

See application file for complete search history.

FIG. 1 is an exploded, front, top perspective view of a wireless earbud set, showing my new design;
FIG. 2 is a front, top perspective view of the case of a wireless earbud set shown separately for ease of illustration;
FIG. 3 is a rear, bottom perspective view thereof;
FIG. 4 is a front elevation view thereof;
FIG. 5 is a rear elevation view thereof;
FIG. 6 is a right side elevation view thereof;
FIG. 7 is a left side elevation view thereof;
FIG. 8 is a top plan view thereof;
FIG. 9 is a bottom plan view thereof;
FIG. 10 is a front elevation view of the left side earbud of the wireless earbud set shown separately for ease of illustration;
FIG. 11 is a rear elevation view thereof;
FIG. 12 is a front elevation view of the right side earbud of the wireless earbud set shown separately for ease of illustration;
FIG. 13 is a rear elevation view thereof;
FIG. 14 is a right side elevation view thereof;
FIG. 15 is a left side elevation view thereof;
FIG. 16 is a top plan view thereof; and,
FIG. 17 is a bottom plan view thereof.
The broken lines depict portions of the wireless earbud set that form no part of the claimed design.

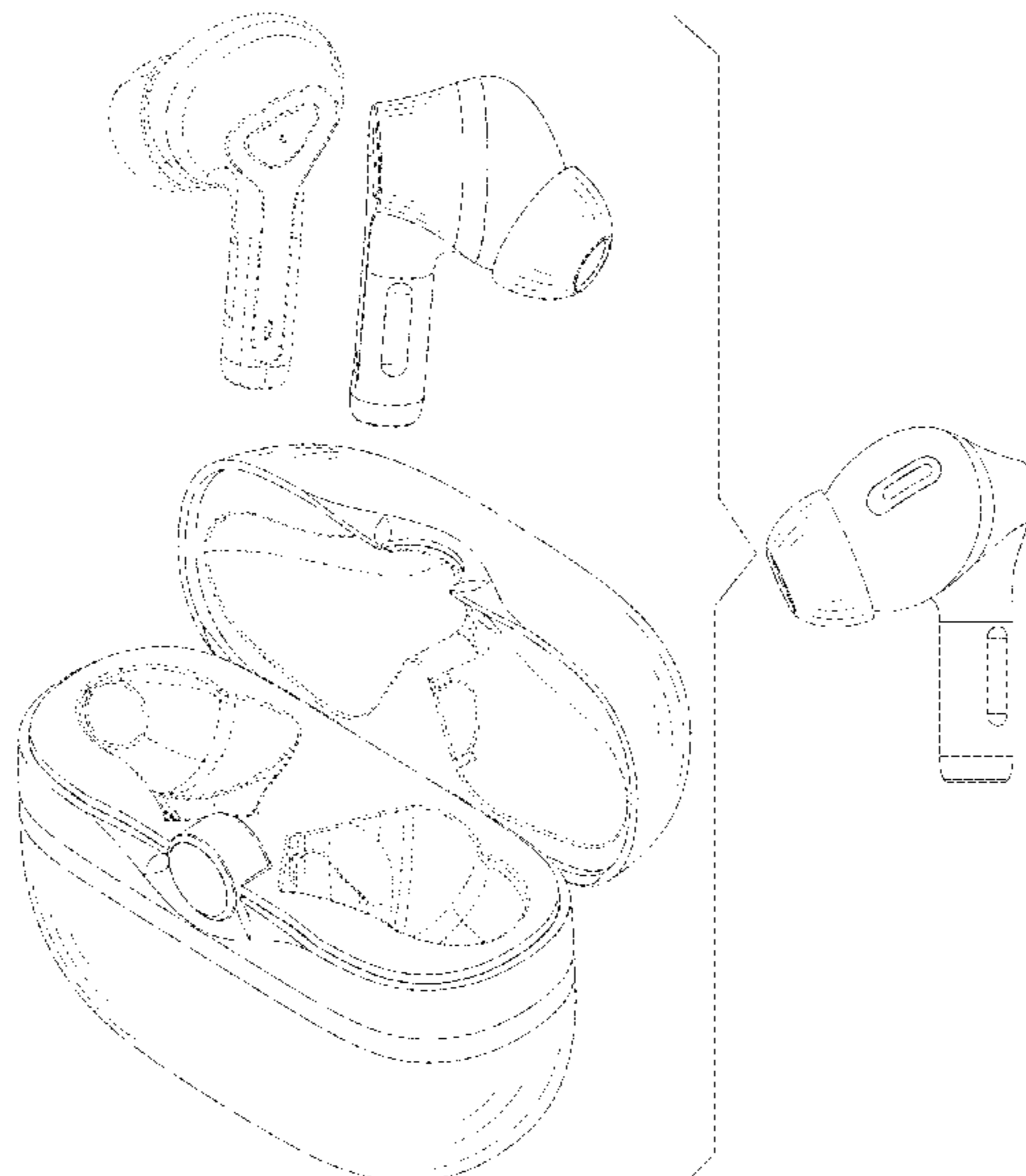
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1 Claim, 13 Drawing Sheets



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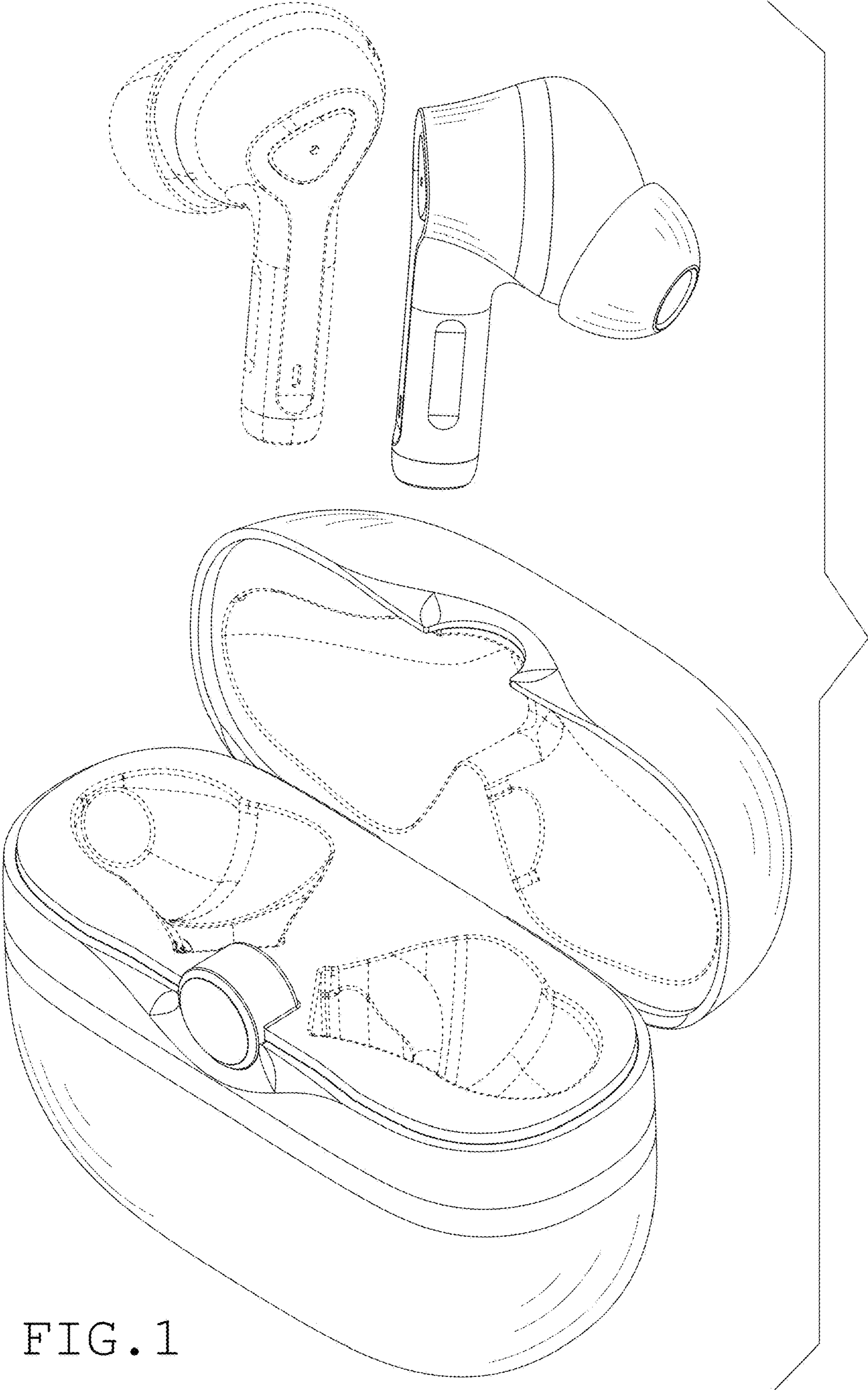
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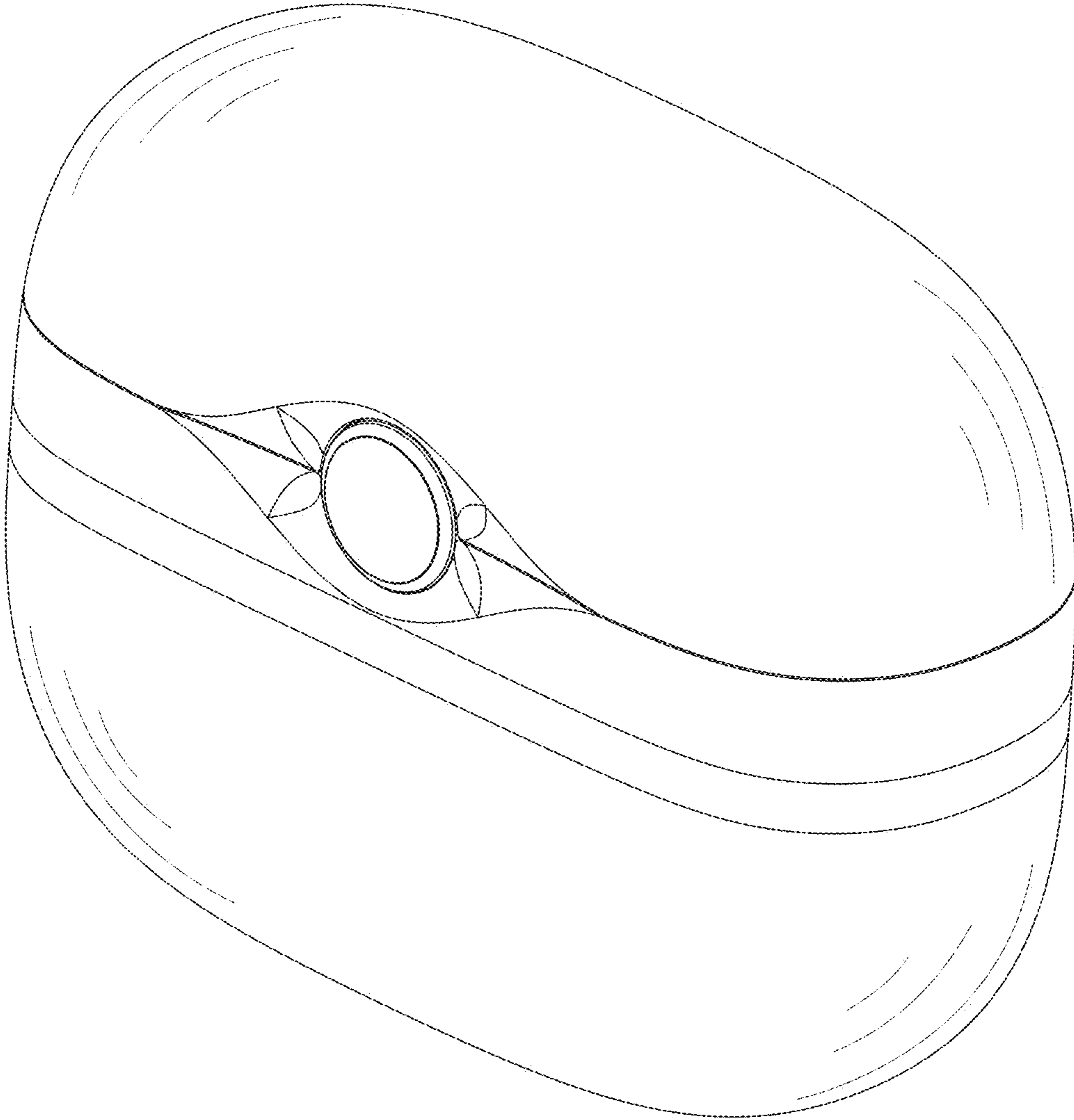


FIG. 2

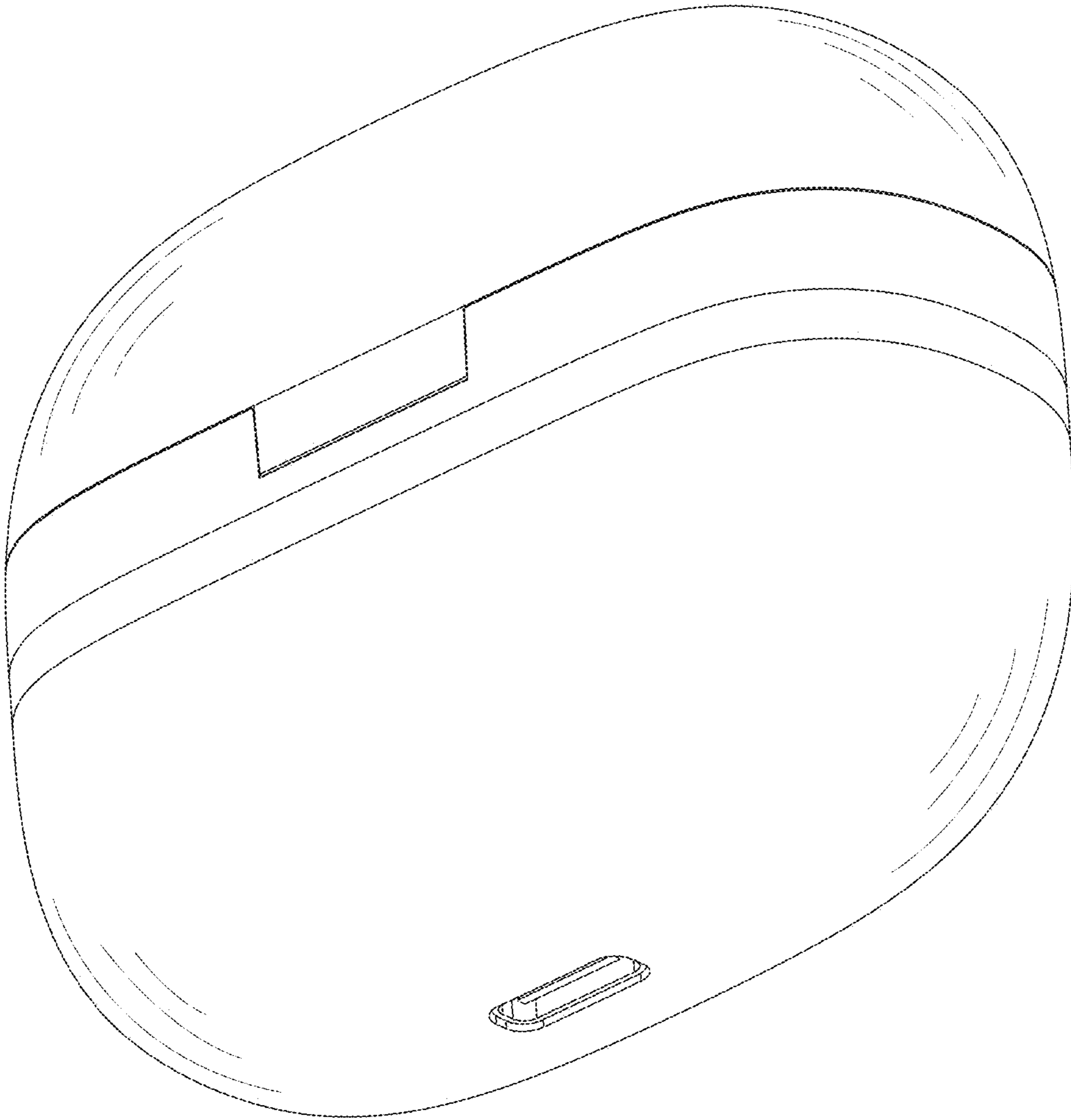


FIG. 3

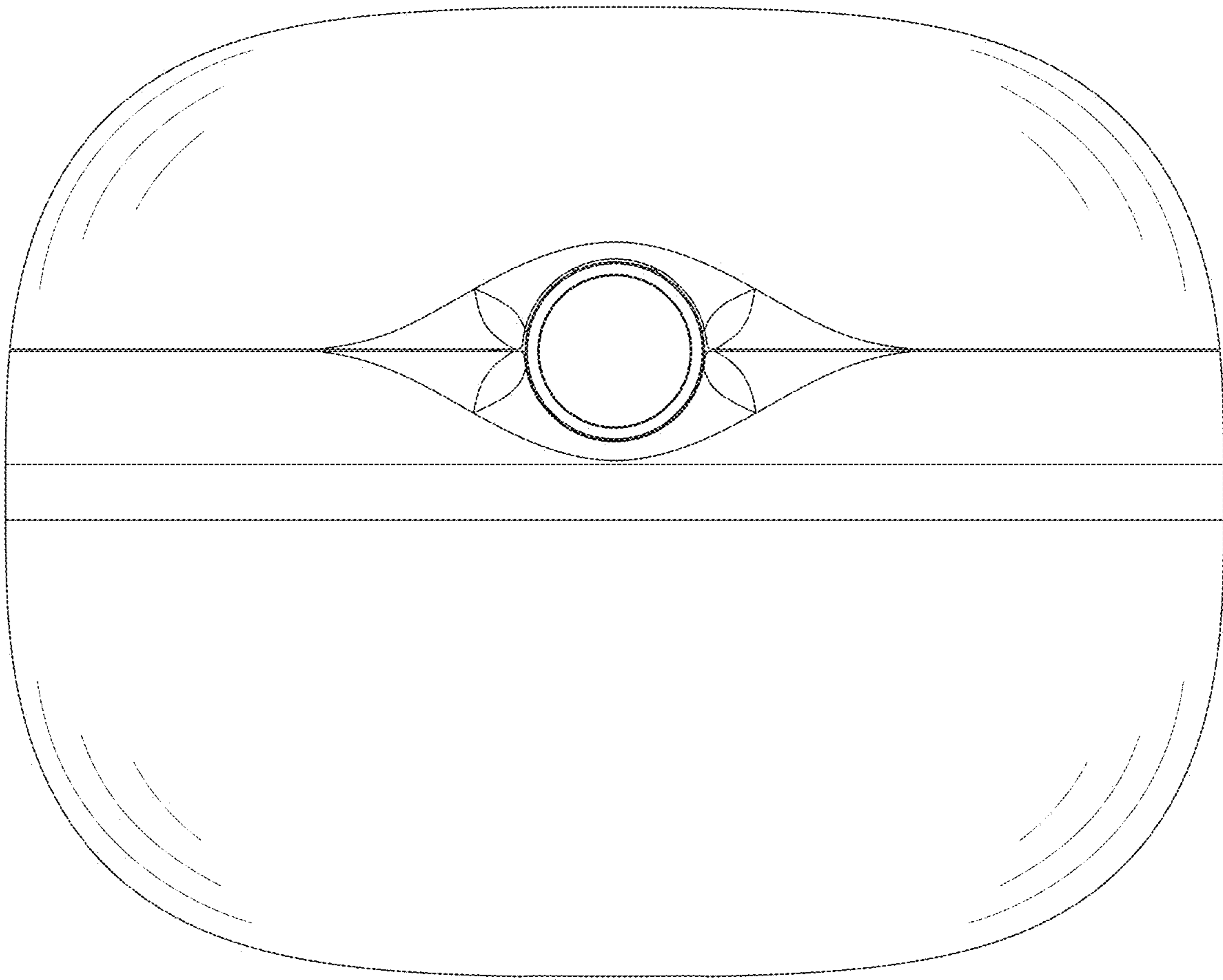


FIG. 4

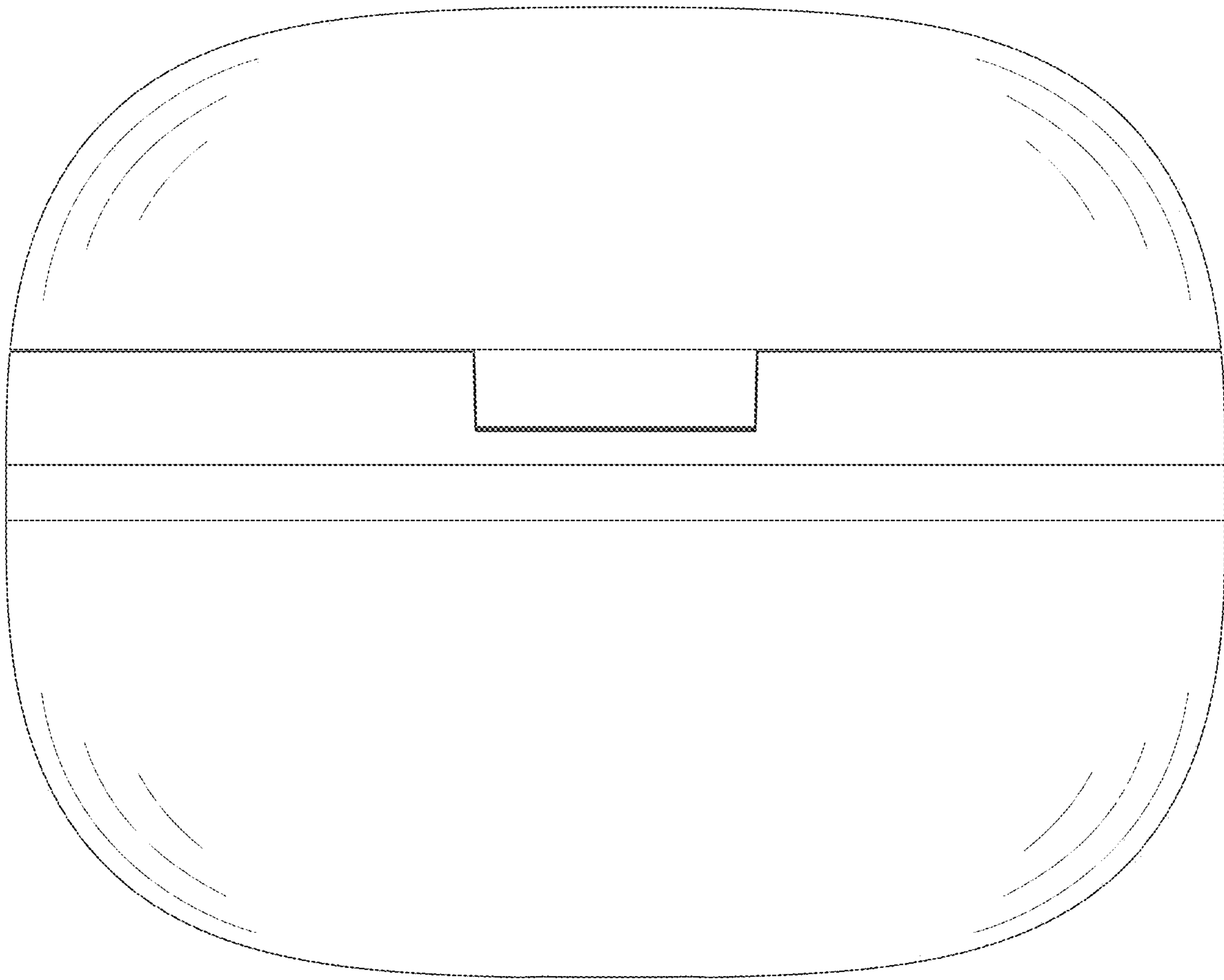


FIG. 5

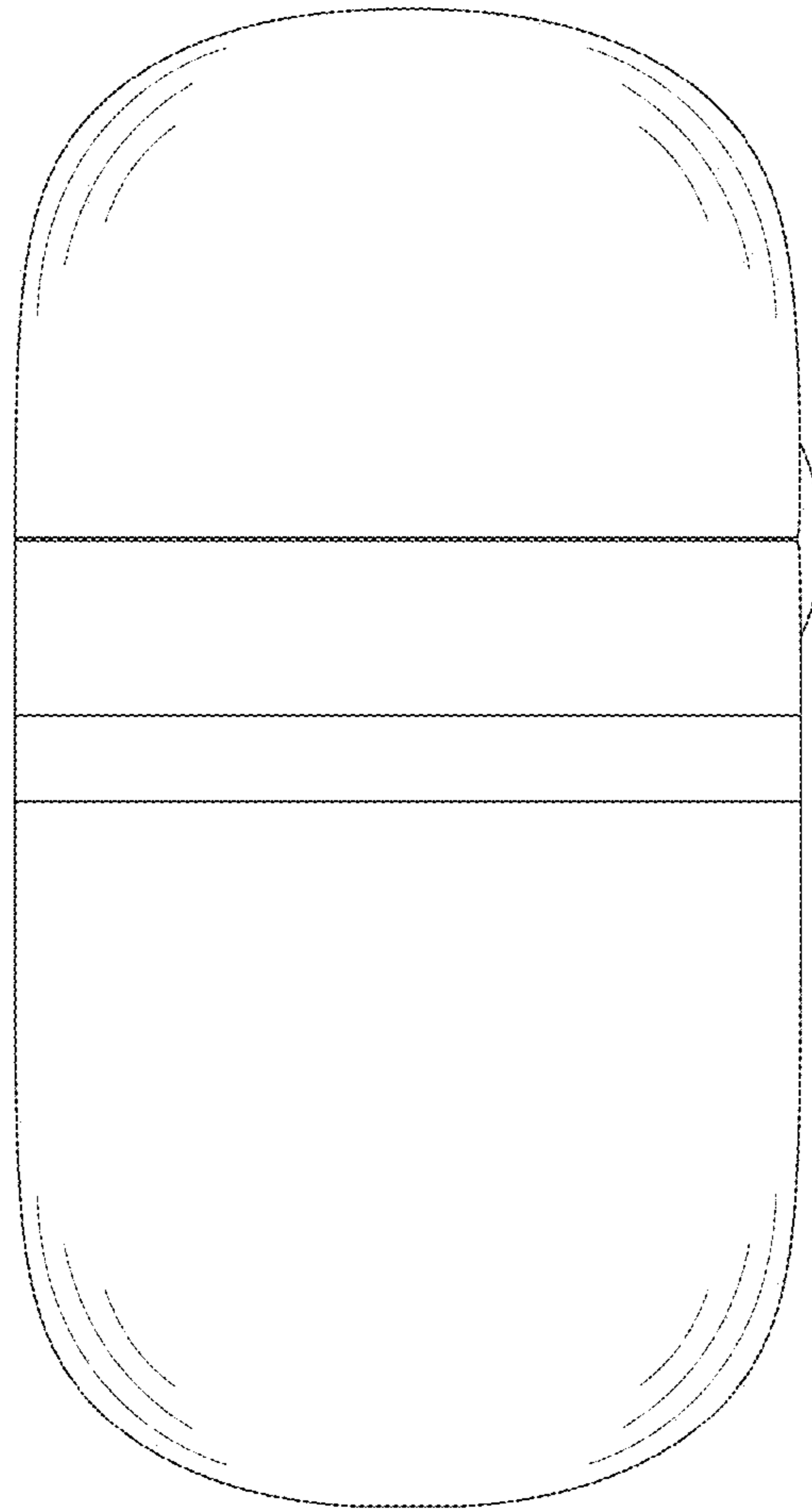


FIG. 6

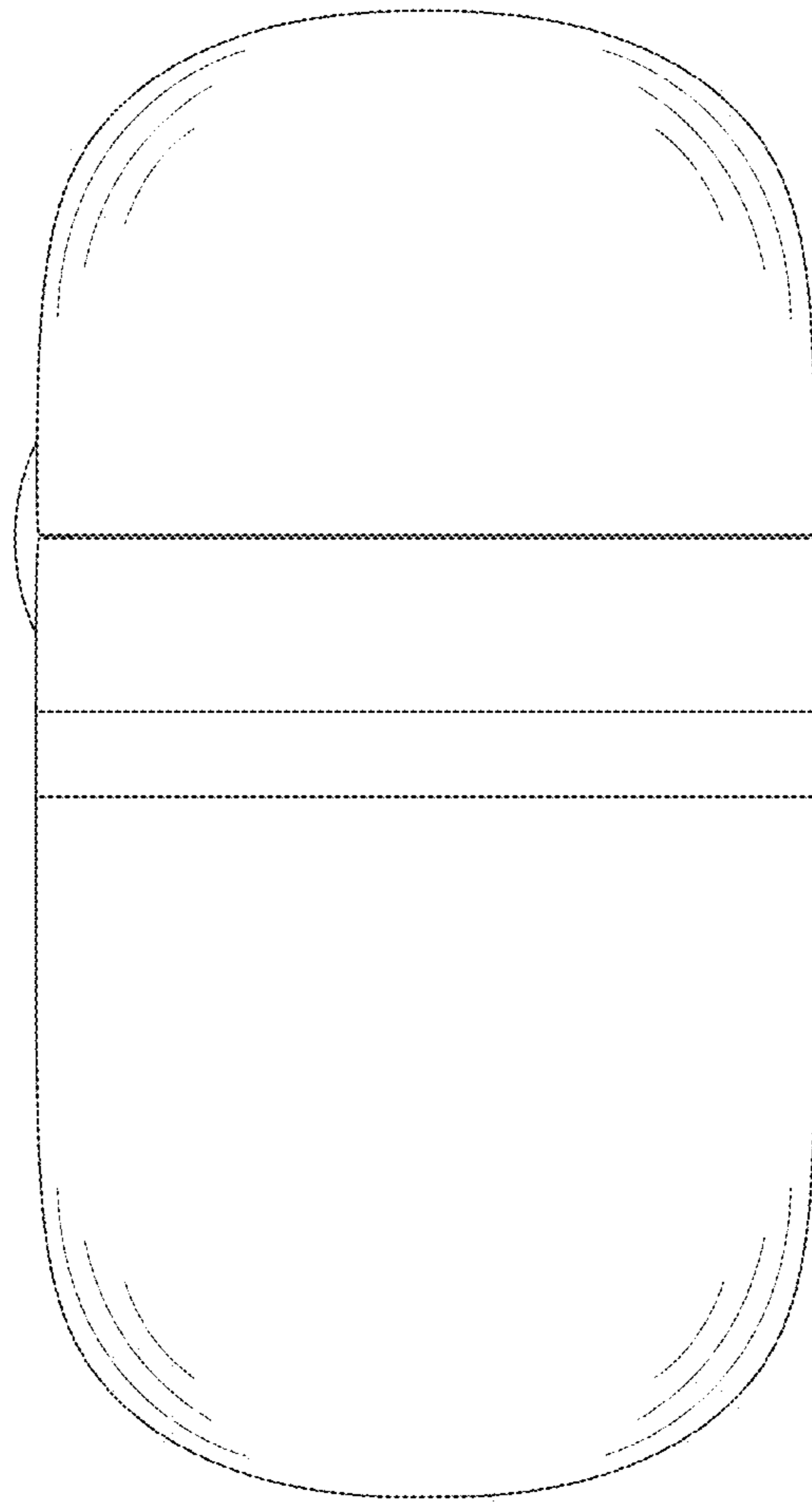


FIG. 7

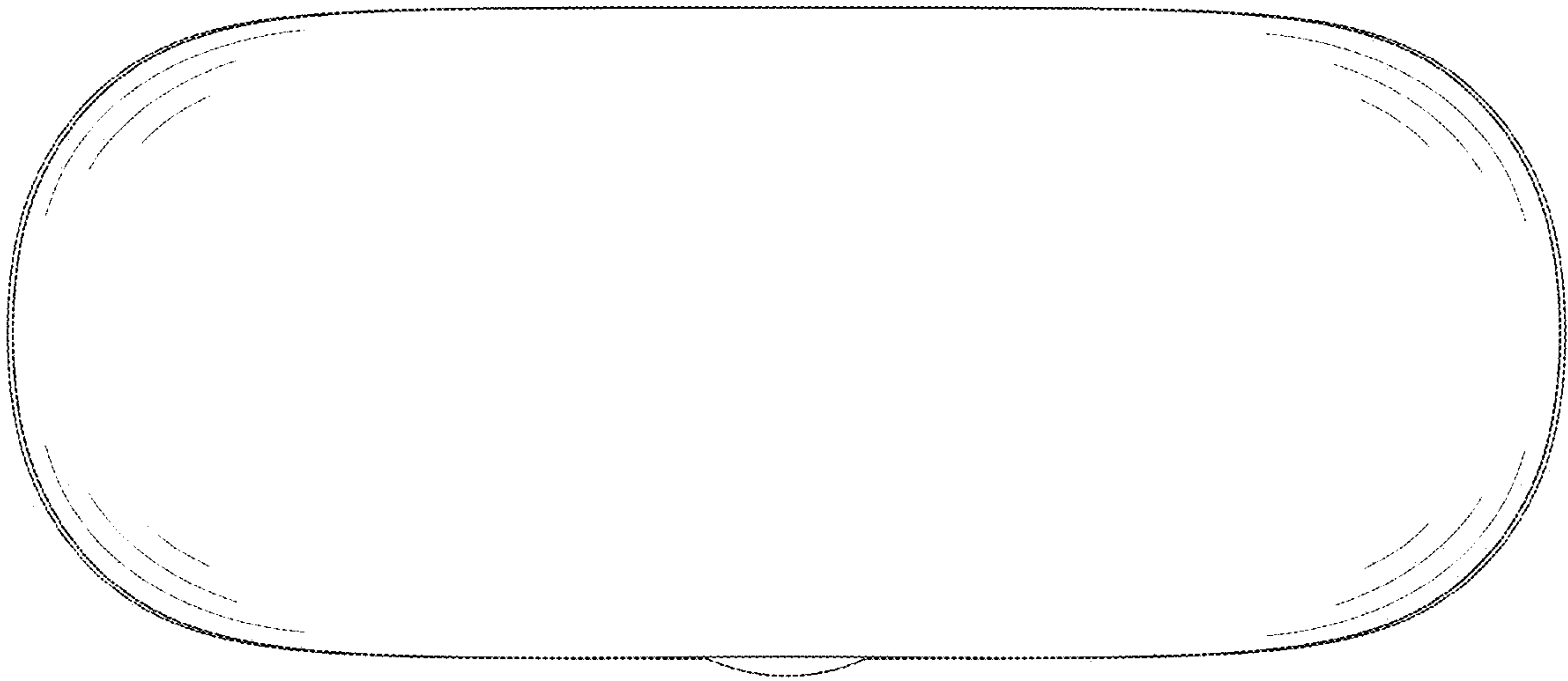


FIG. 8

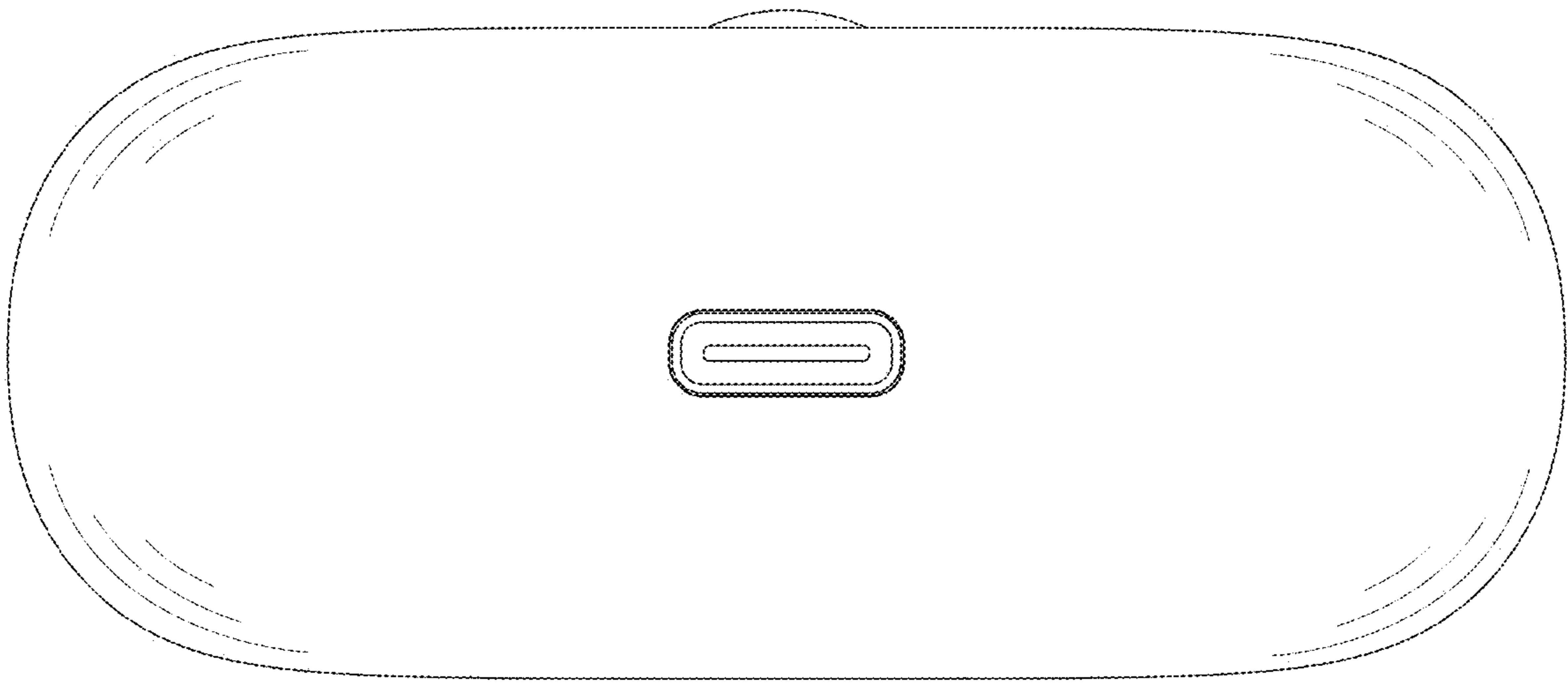


FIG. 9

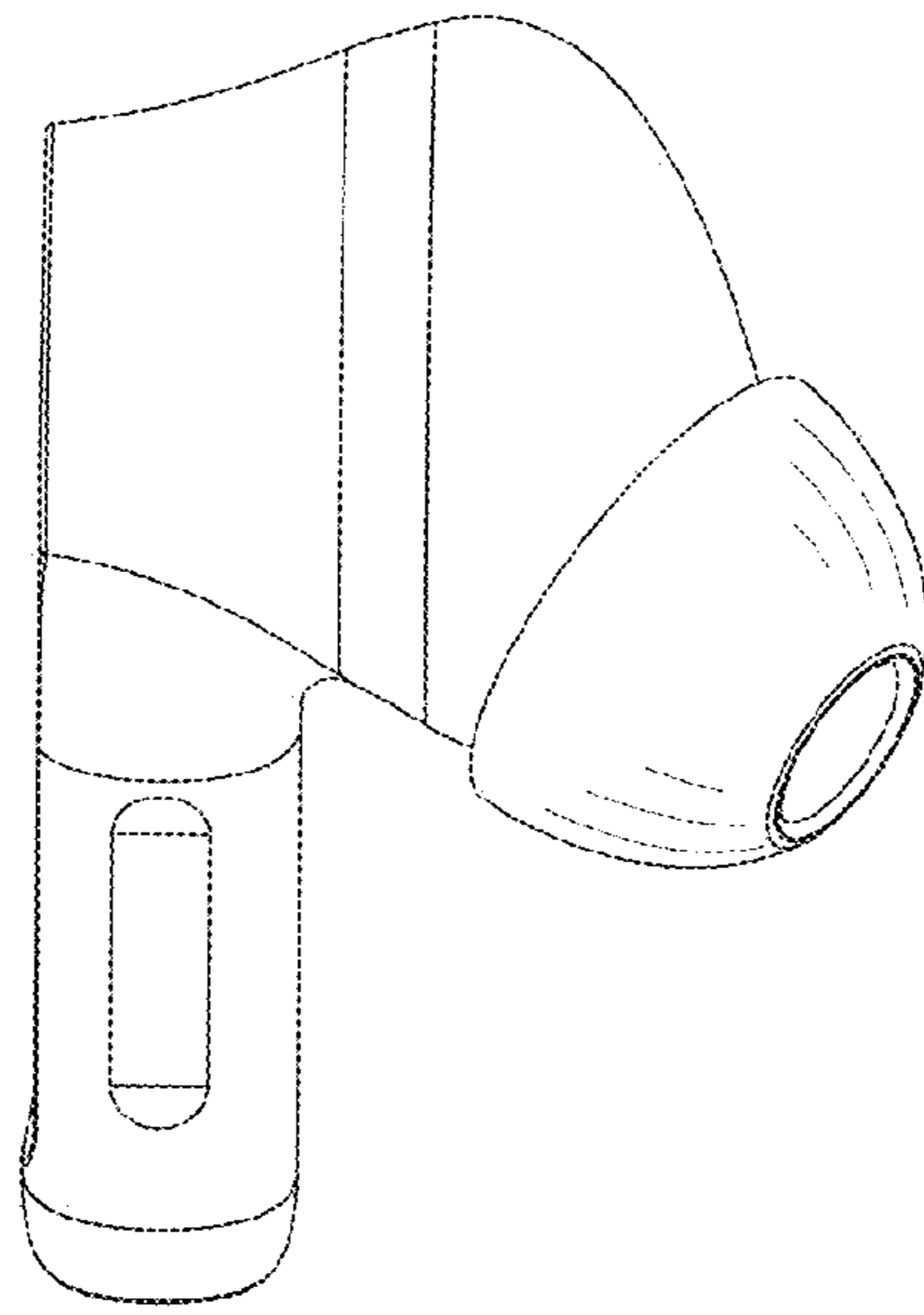


FIG. 10

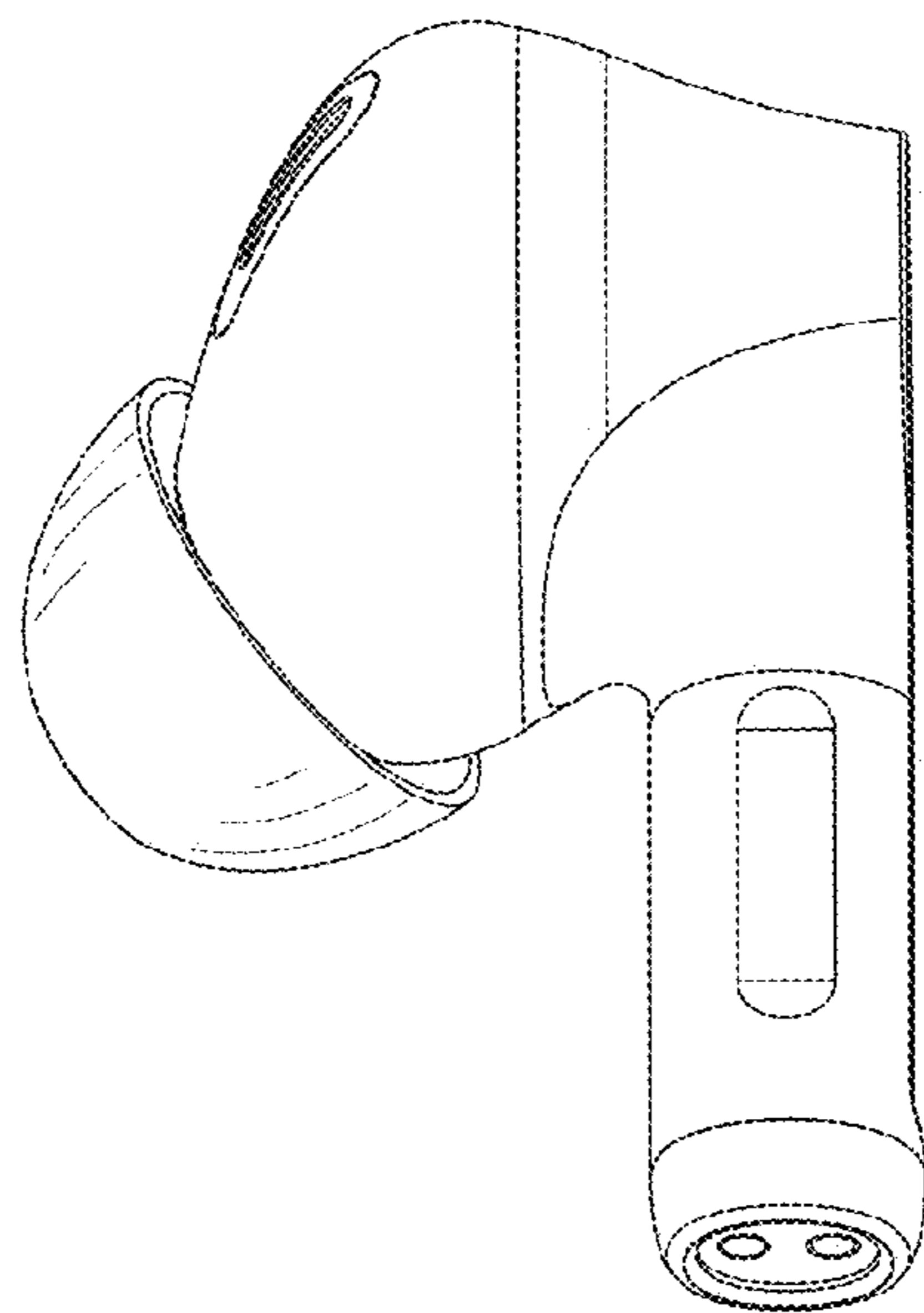


FIG. 11

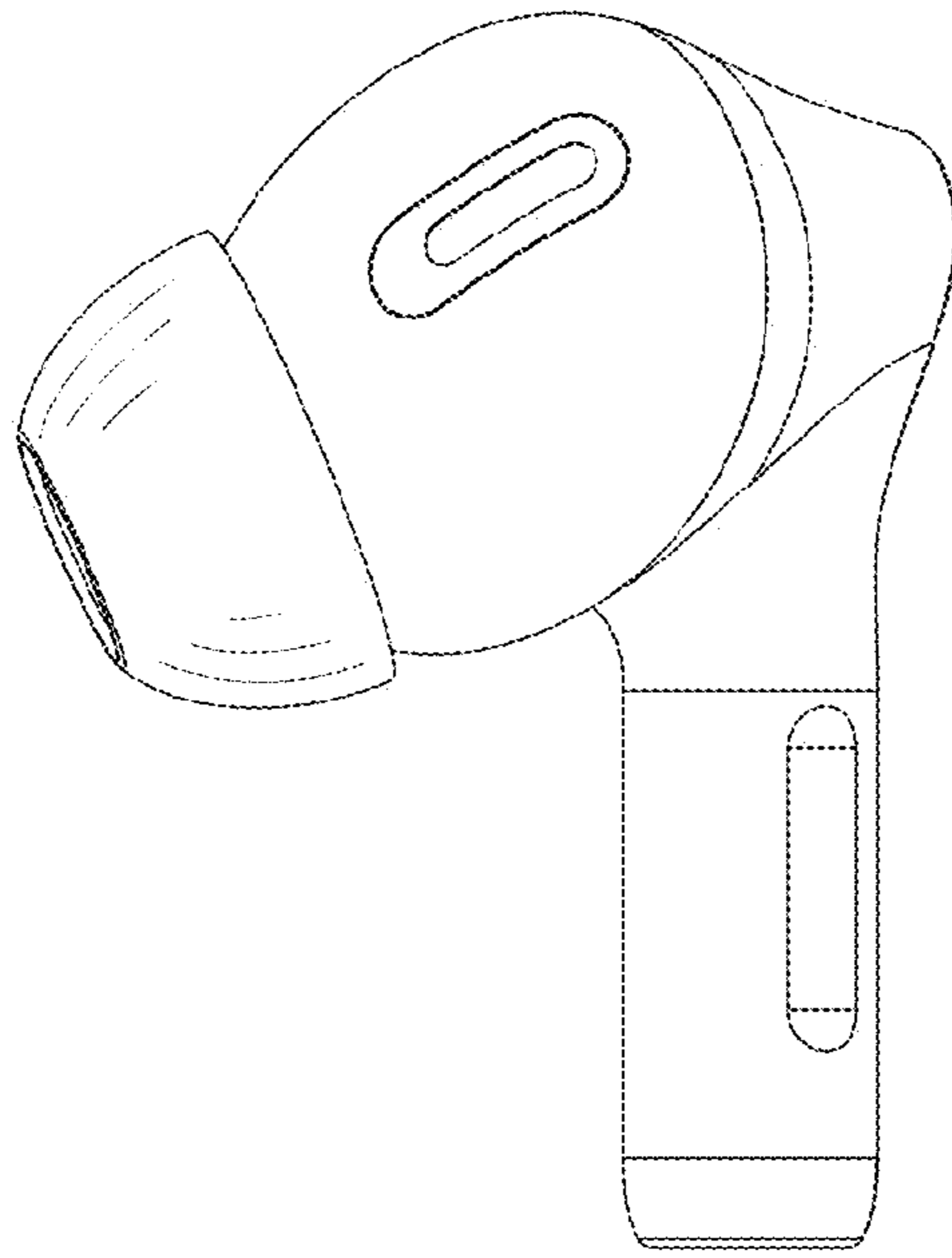


FIG. 12

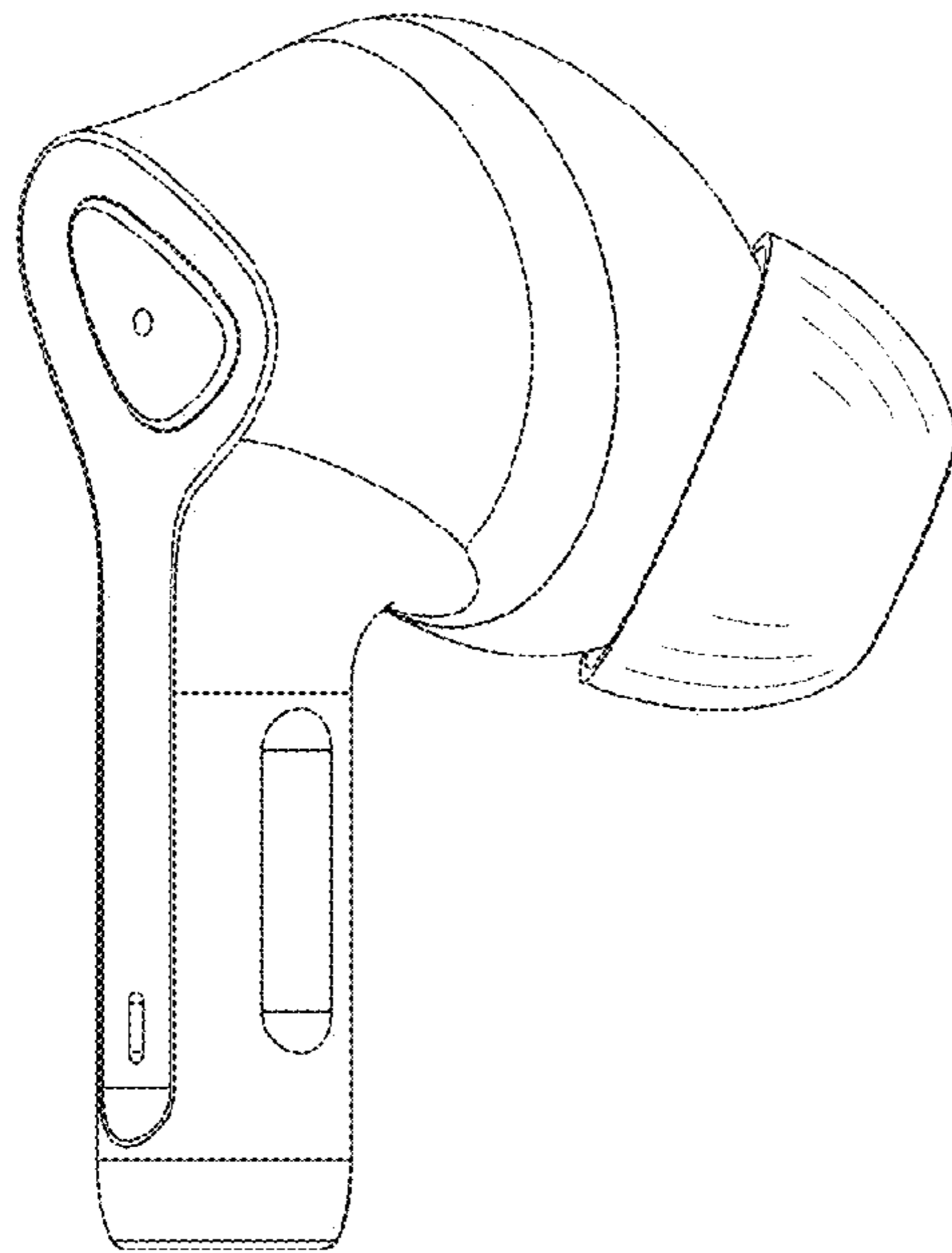


FIG. 13

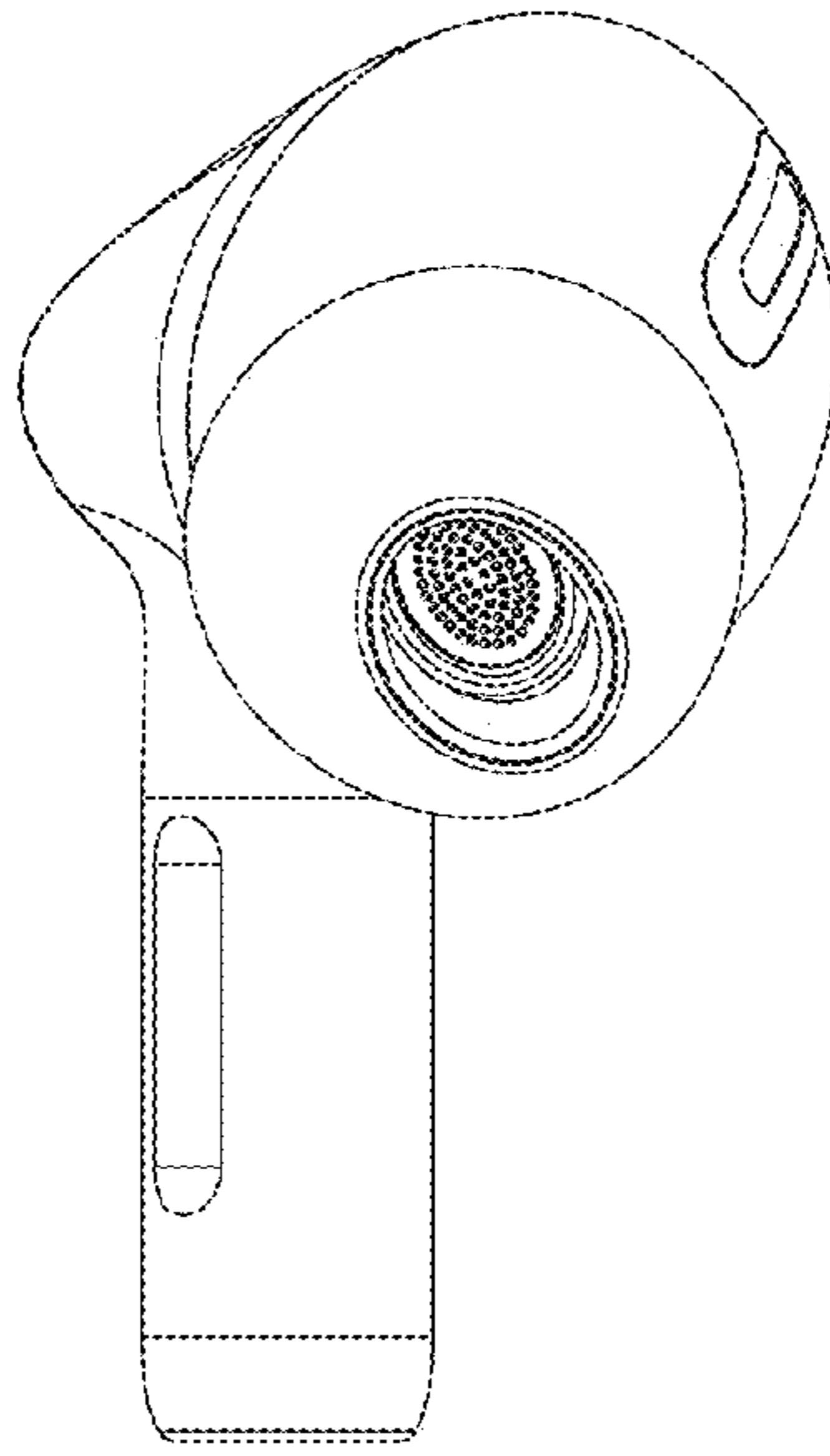


FIG. 14

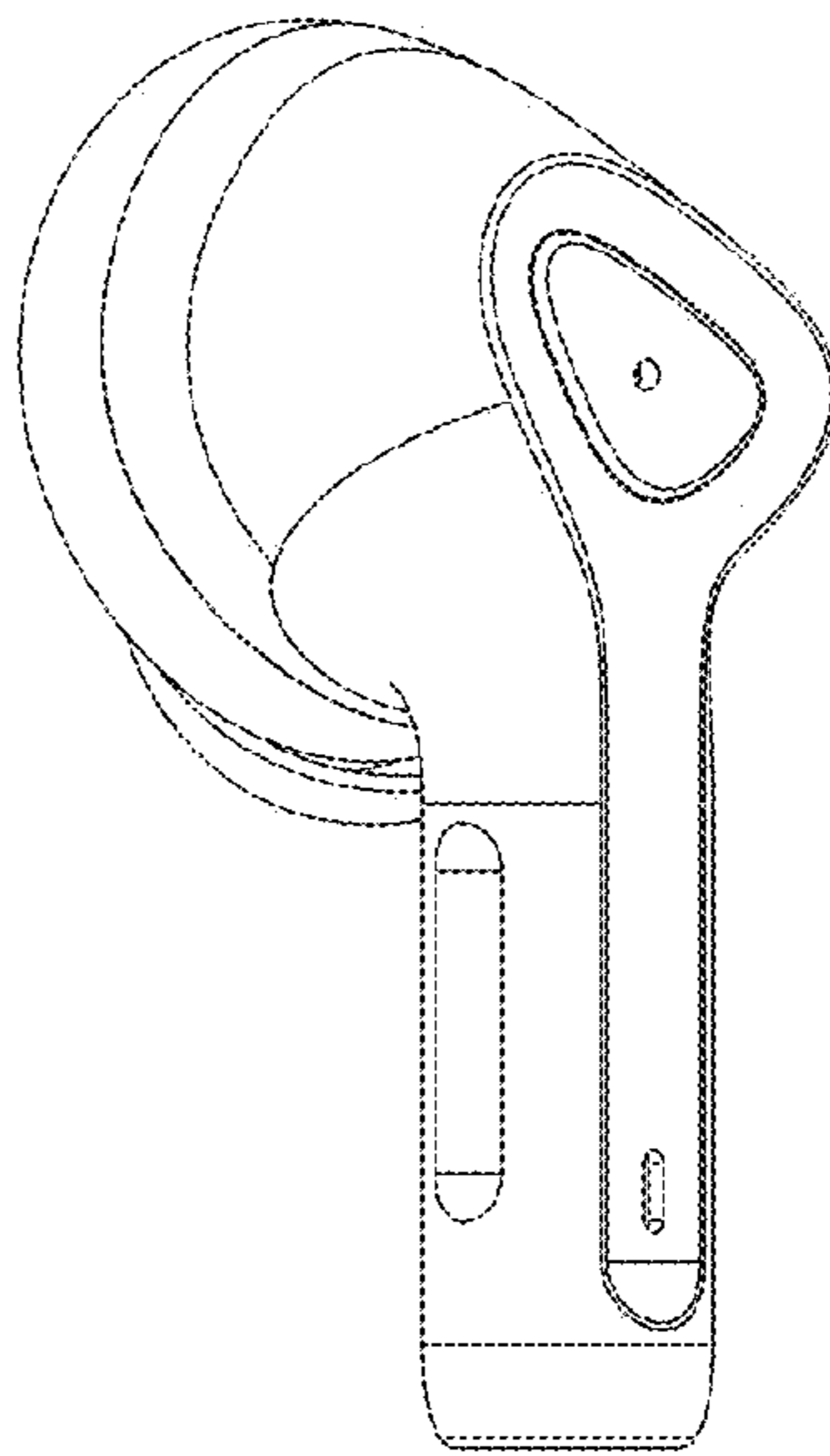


FIG. 15

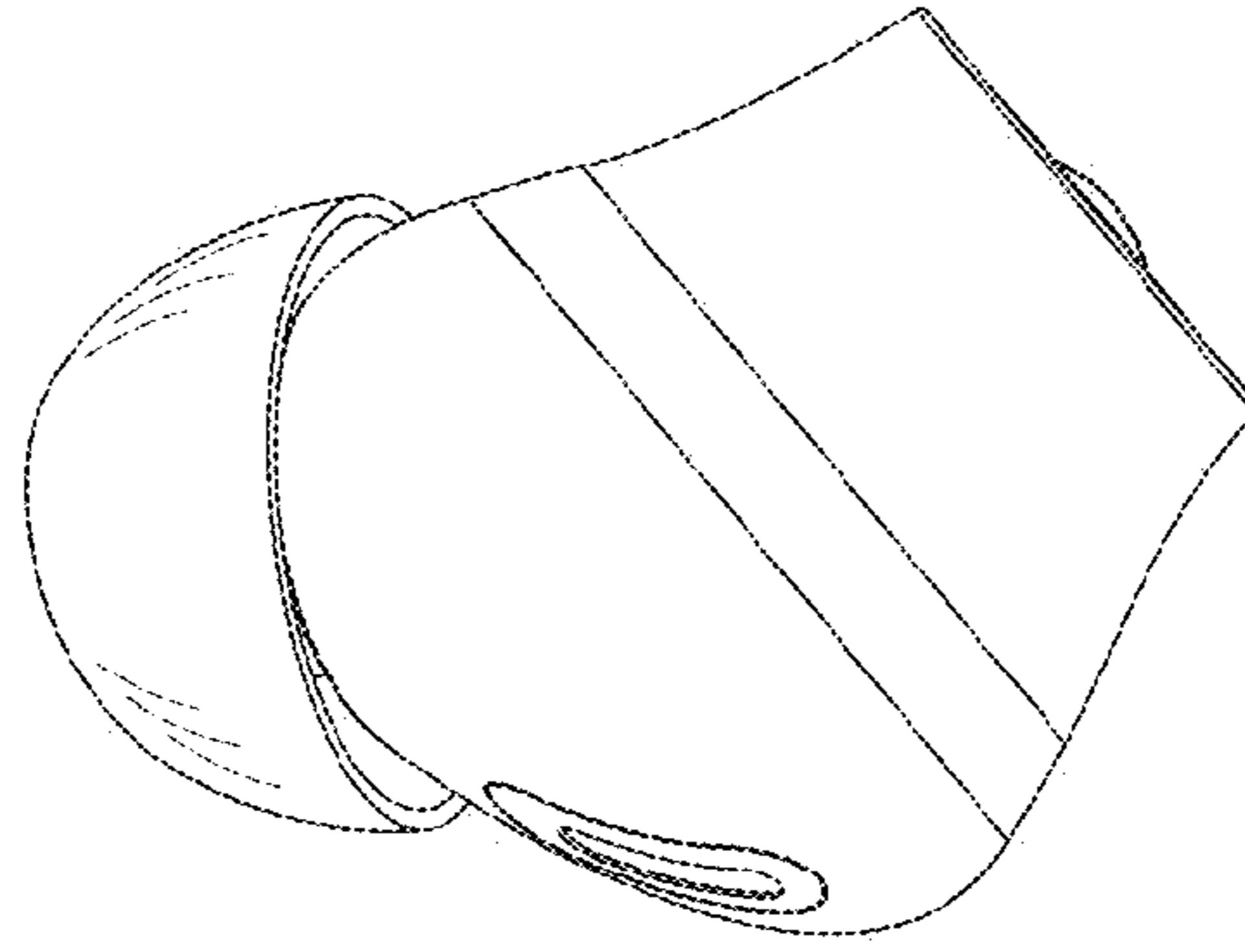


FIG. 16

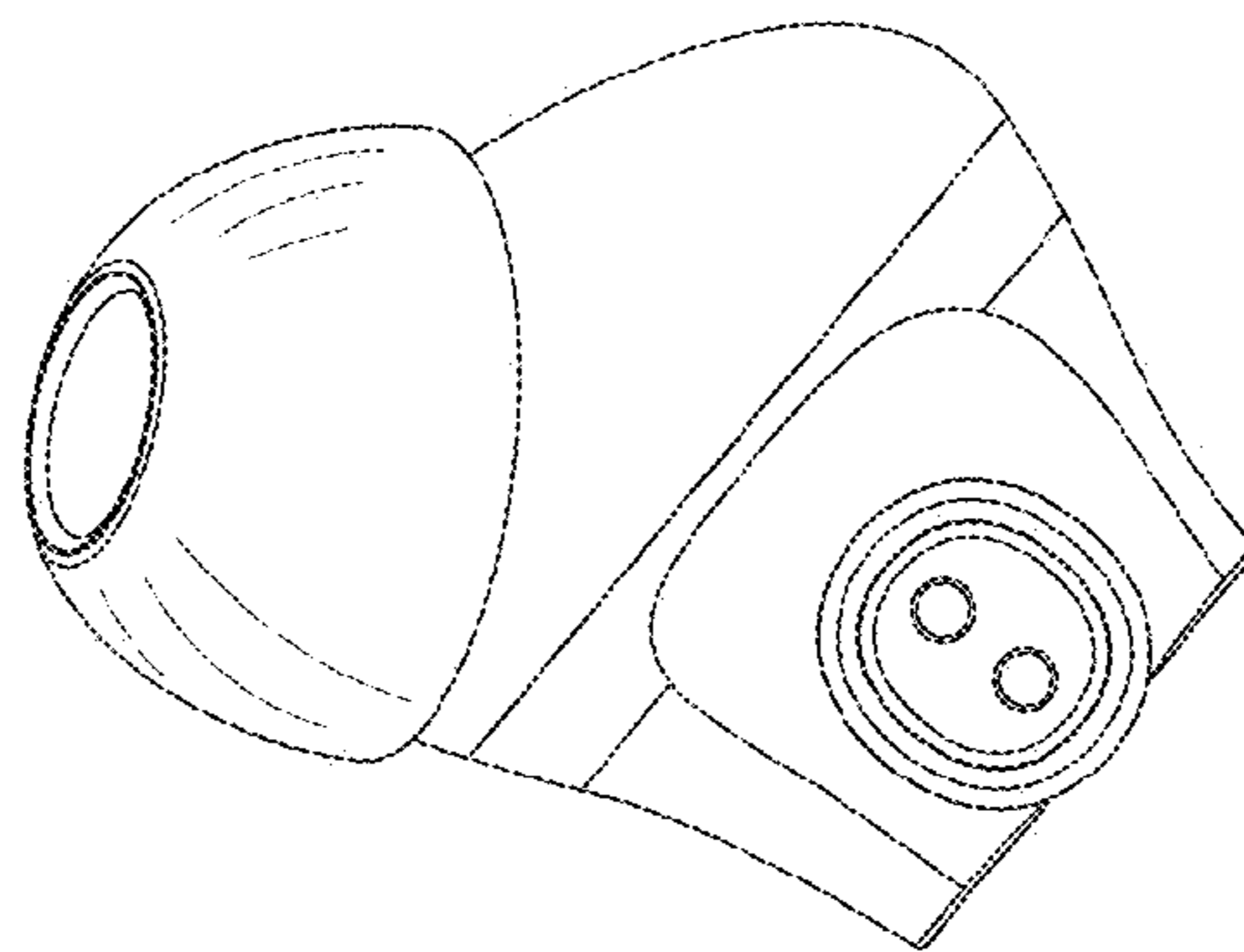


FIG. 17